

Chip Ferrite Bead For High Speed

MCB 1005-2012 H Series

RELIABILITY AND TEST CONDITION

Test item	Test condition	Criteria
Temperature Cycle	A. Temperature : -40 ~ +85°C B. Cycle : 100 cycles C. Dwell time : 30minutes Measurement : at ambient temperature 24 hrs after test completion	A. No mechanical damage B. Impedance value should be within ± 20 % of the initial value
Operational Life	A. Temperature : 125°C ± 5°C B. Test time : 1000 hrs C. Apply current : full rated current Measurement : at ambient temperature 24 hrs after test completion	A. No mechanical damage B. Impedance value should be within ± 20 % of the initial value
Biased Humidity	A. Temperature : 40 ± 2°C B. Humidity : 90 ~ 95 % RH C. Test time : 1000 hrs D. Apply current : full rated current Measurement : at ambient temperature 24 hrs after test completion	A. No mechanical damage B. Impedance value should be within ± 20 % of the initial value
Resistance to Solder Heat	A. Solder temperature : 260 ± 5°C B. Flux : Rosin C. DIP time : 10 ± 1 sec	A. More than 95 % of terminal electrode should be covered with new solder B. No mechanical damage C. Impedance value should be within ± 20 % of the initial value
Steam Aging Test	A. Temperature : 93 ± 2°C B. Test time : 4 hrs C. Solder temperature : 235 ± 5°C D. Flux : Rosin E. DIP time : 5 ± 1 sec	More than 95 % of terminal electrode should be covered with new solder